

Quantum[™] SA.45s CSAC

Chip Scale Atomic Clock





Microsemi invented portable atomic timekeeping with QUANTUM™, the world's first family of miniature and chip scale atomic clocks.

Choose QUANTUM™ class for best-inclass stability, size, weight, and power consumption.

With an extremely low power consumption of <120 mW and a volume of <17 cc, the Microsemi SA.45s Chip Scale Atomic Clock (CSAC) brings the accuracy and stability of an atomic clock to portable applications for the first time.

The SA.45s provides 10 MHz and 1 PPS outputs at standard CMOS levels, with short-term stability (Allan Deviation) of $3.0E^{-10}$ @ TAU = 1 sec, typical long-term aging of $<9E^{-10}/month$, and maximum frequency change of $\pm 5E^{-10}$ over an operating temperature range of -10 °C to 70 °C.

The SA.45s CSAC accepts a 1 PPS input that may be used to synchronize the unit's 1 PPS output to an external reference clock with ± 100 ns accuracy. It also use the 1 PPS input to discipline its phase and frequency to within 1 ns and $1.0E^{-12}$, respectively.

A standard CMOS-level RS-232 serial interface is built in to the SA.45s. This is used to control and calibrate the unit and also to provide a comprehensive set of status monitors. The interface is also used to set and read the CSAC's internal time-of-day clock.

Features

- Power consumption <120 mW
- Less than 17 cc volume, 1.6" x 1.39" x 0.45"
- 10 MHz CMOS-compatible output
- 1 PPS output and 1 PPS input for synchronization
- RS-232 interface for monitoring and control
- Short term stability (Allan Deviation) of 3.0E⁻¹⁰@ TAU =1 sec

Applications*

- GPS receivers
- Backpack radios
- Anti-IED jamming systems
- Autonomous sensor networks
- Unmanned vehicles
- Underwater sensor systems
- Stability for various other communication and transmission applications

*The Chip Scale Atomic Clock is not tested, qualified, and rated for space applications



Quantum™ SA.45s CSAC

Chip Scale Atomic Clock

Options to Meet a Wider Range of Applications

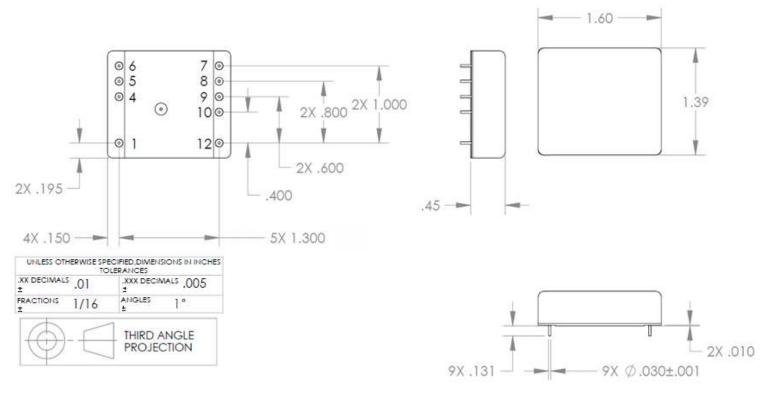
Following are the different SA.45s CSAC options with there output frequencies.

Options	Output Frequency
001	10 MHz
003	16.384 MHz
004	10.24 MHz
006	5 MHz

For other output frequencies please contact Microsemi for details.

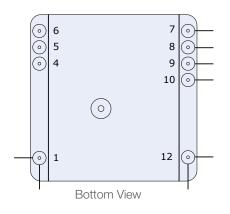
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Mechanical Interface



Pin Description

Pin Number	I.D.
1	Tune
2	N/A
3	N/A
4	BITE
5	Tx
6	Rx
7	Vcc
8	GND
9	1 PPS IN
10	1 PPS OUT
11	N/A
12	10 MHz OUT





Part number 090-02984-001

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

•	Frequency	10 MHz
•	Format	CMOS
•	Amplitude	0 V to Vcc
•	Load impedance	1 MΩ
•	Quantity	1

1 PPS Output

•	Rise/fall time (10%-90%)	
	at load capacitance 10 pF	<10 ns
•	Pulse width	100 µs
•	Level	0 V to Vcc
•	Logic High (V₀H) min	2.80 V
•	Logic Low (VoL) max	0.30 V
•	Load impedance	1 MΩ
•	Quantity	1

1 PPS Input

•	Format	Rising edge
•	Low level	<0.5 V
•	High level	2.5 V to Vcc
•	Input impedance	1 MΩ
•	Quantity	1

Serial Communications

•	Protocol	RS232
•	Format	CMOS 0 V to Vcc
•	Tx/Rx impedance	1 ΜΩ
•	Baud rate	57600

Built-in Test Equipment (BITE) output

•	Load impedance	1 ΜΩ
•	Logic	0 = Normal operation
		1 = Alarm

CMOS 0 V to Vcc

Power Input

Format

	-	
•	Operating	<120 mW
•	Warmup	<140 mW
•	Input voltage (Vcc)	$3.3 \pm 0.1 \text{VDC}$

Physical Specifications

	•	
•	Size	1.6" x 1.39" x 0.45"
•	Weight	<35 g
•	MTBF	>100.000 hours

Environmental Specification

Operating

•	Operating temperature	-10	°C to	70	$^{\circ}C$
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[•] Maximum frequency change over operating temp range

(max. rate of change	
0.5 °C/minute)	$\pm 5 \times 10^{-10}$

Frequency change over

allowable input voltage range $\pm 4 \times 10^{-10}$

Magnetic sensitivity (≤2.0 Gauss) ±9x10⁻¹¹/Gauss

 Radiated emissions Compliant to FCC part 15, Class B, when mounted

properly onto host PCB.

 Vibration Maintains lock under

MIL-STD-810, Method 514.5, Procedure 1, 7.7 grms

0 to 95% RH per Humidity

MIL-STD-810, Method 507.4.

Storage and Transport (non-operating)

•	Temperature	−55 °C to 85 °C
•	Shock (1 ms half-sine)	1000 g

 Vibration MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

Performance Parameters

Stability (Allan Deviation) ADEV

•	TAU = 1 sec	3.0x10 ⁻¹⁰
•	TAU = 10 sec	1.0x10 ⁻¹⁰
•	TAU = 100 sec	3.0x10 ⁻¹¹
•	TAU = 1000 sec	1.0x10 ⁻¹¹

RF Output Phase Noise (SSB)

•	1 Hz	<-50 dBc/Hz
•	10 Hz	<-70 dBc/Hz
•	100 Hz	<-113 dBc/Hz
•	1000 Hz	<-128 dBc/Hz
•	10000 Hz	<-135 dBc/Hz
•	100,000 Hz	<-140 dBc/Hz

Frequency Accuracy

•	Maximum offset at shipment	$\pm 5 \times 10^{-11}$
•	Maximum retrace (48 hrs off)	$\pm 5 \times 10^{-10}$
	Aging monthly*	<0v10-10 typic

<9x10⁻¹⁰ typical** Aging, monthly' <1x10⁻⁸ typical** Aging, yearly* • 1 PPS Sync. ±100 ns

(*After 30 days of continuous operation)

Digital Tuning

•	Range	±2x10 ⁻⁸
•	Resolution	1x10 ⁻¹²

Analog Tuning

•	Range	±2.2x10 ⁻⁸
•	Resolution	1x10 ⁻¹¹

0-2.5 V into $100 \text{ k}\Omega$ Input

Warm-up Time < 180 s

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

^{**} All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Part number 090-02984-003

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

16.384 MHz Frequency Format CMOS Amplitude 0 V to Vcc Load impedance 1 $M\Omega$ Quantity 1

1 PPS Output

• Rise/fall time (10%-90%) at load capacitance 10 pF <10 ns Pulse width 97.656 us Level 0 V to Vcc • Logic High (VoH) min 2.80 V Logic Low (Vol) max 0.30 V Load impedance 1 MΩ Quantity 1

1 PPS Input

 Format Rising edge < 0.5 V Low level High level 2.5 V to Vcc Input impedance 1 ΜΩ Quantity 1

Serial Communications

 Protocol RS-232 CMOS 0 V to Vcc Format • Tx/Rx impedance 1 ΜΩ

 Baud rate 57600

Built-in Test Equipment (BITE) output

 Format CMOS 0 V to Vcc

 Load impedance 1 MO

0 = Normal operation Logic

1 = Alarm

Power Input

 Operating <120 mW Warmup <140 mW • Input Voltage (Vcc) $3.3 \pm 0.1 \text{ VDC}$

Physical Specifications

 Size 1.6" x 1.39" x 0.45"

 Weight < 35 q

MTBF >100,000 hours

Environmental Specification

Operating

-10 °C to 70 °C Operating temperature

 Maximum frequency change over operating temp range

(max. rate of change 0.5 °C/minute)

 $\pm 5x10^{-10}$

Frequency change over

allowable input voltage range $\pm 4 \times 10^{-10}$

Magnetic sensitivity (≤2.0 Gauss) ±9x10⁻¹¹/Gauss

 Radiated emissions Compliant to FCC part 15,

> Class B, when mounted properly onto host PCB.

 Vibration Maintains lock under

MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

0 to 95% RH per Humidity

MIL-STD-810, Method 507.4.

Storage and Transport (non-operating)

 Temperature -55 °C to 85 °C

• Shock (1 ms half-sine) 1000 g

 Vibration MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

Performance Parameters

Stability (Allan Deviation) ADEV

 $3.0x10^{-10}$ • TAU = 1 sec • TAU = 10 sec 1.0x10⁻¹⁰ • TAU = 100 sec $3.0x10^{-11}$ • TAU = 1000 sec 1.0x10⁻¹¹

RF Output Phase Noise (SSB)

• 1 Hz <-46 dBc/Hz • 10 Hz <-66 dBc/Hz • 100 Hz <-110 dBc/Hz • 1000 Hz <-128 dBc/Hz • 10000 Hz <-135 dBc/Hz <-140 dBc/Hz • 100,000 Hz

Frequency Accuracy

 Maximum offset at shipment $\pm 5x10^{-11}$ • Maximum retrace (48 hrs off): $\pm 5x10^{-10}$

· Aging, monthly* <9x10⁻¹⁰ typical** <1x10⁻⁸ typical** Aging, yearly* ±100 ns

• 1 PPS Sync.

(*After 30 days of continuous operation)

Digital Tuning

 $\pm 2x10^{-8}$ Range Resolution 1x10⁻¹²

Analog Tuning

 Range ±2.2x10⁻⁸ 1x10⁻¹¹ Resolution

Input 0-2.5 V into $100 \text{ k}\Omega$

Warm-up Time < 180 s

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

^{**} All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Part number 090-02984-004

Specification

All specifications at 25 °C, V_{cc} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

Frequency
 Format
 Amplitude
 Load impedance
 Quantity
 10.24 MHz
 CMOS
 0 V to V_{cc}
 1 MΩ

1 PPS Output

Rise/fall time (10%-90%) at load capacitance 10 pF
Pulse width
Level
Logic High (VoH) min
Logic Low (VoL) max
Load impedance
Quantity
100 μs
0 V to Vcc
2.80 V
0.30 V
1 MΩ

1 PPS Input

Format

 Low level
 High level
 Input impedance
 Quantity

 Rising edge
 2.5 V
 IV
 IV
 IMΩ

Serial Communications

Protocol RS-232
 Format CMOS 0 V to Vcc
 Tx/Rx impedance 1 MΩ
 Baud rate 57600

Built-in Test Equipment (BITE) output

 $\begin{array}{ll} \bullet & \text{Format} & \text{CMOS 0 V to V}_{\text{CC}} \\ \bullet & \text{Load impedance} & 1 \text{ M}\Omega \\ \bullet & \text{Logic} & 0 = \text{Normal operation} \\ & 1 = \text{Alarm} \\ \end{array}$

Power Input

Operating
 Warmup
 Input Voltage (V_{cc})
 2120 mW
 140 mW
 3.3 ± 0.1 VDC

Physical Specifications

• Size 1.6" x 1.39" x 0.45"

• Weight <35 g

• MTBF >100,000 hours

Environmental Specification

Operating

Operating temperature –10 °C to 70 °C

 Maximum frequency change over operating temp range (max. rate of change

0.5 °C/minute) $\pm 5x10^{-10}$

Frequency change over

allowable input voltage range $\pm 4x10^{-10}$

Magnetic sensitivity (≤2.0 Gauss) ±9x10⁻¹¹/Gauss

Radiated emissions
 Compliant to FCC part 15,

Class B, when mounted properly onto host PCB.

Vibration
 Maintains lock under

MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

Humidity
 0 to 95% RH per

MIL-STD-810, Method 507.4.

Storage and Transport (non-operating)

• Temperature -55 °C to 85 °C

• Shock (1 ms half-sine) 1000 g

• Vibration MIL-STD-810,Method 514.5,

Procedure 1, 7.7 grms

Performance Parameters

Stability (Allan Deviation) ADEV

TAU = 1 sec
 TAU = 10 sec
 TAU = 100 sec
 TAU = 1000 sec
 TAU = 1000 sec
 1.0x10⁻¹⁰
 TAU = 1000 sec
 1.0x10⁻¹¹

RF Output Phase Noise (SSB)

1 Hz
 10 Hz
 10 Hz
 100 Hz
 1000 Hz
 1000 Hz
 10000 Hz
 10000 Hz
 100,000 Hz

Frequency Accuracy

Maximum offset at shipment ±5x10⁻¹¹
 Maximum retrace (48 hrs off) ±5x10⁻¹⁰

Aging, monthly*
 Aging, yearly*
 1 PPS Sync.
 49x10⁻¹⁰ typical**
 1x10⁻⁸ typical**
 ±100 ns

• 1 PP3 Sync. ±100 ns

(*After 30 days of continuous operation)

Digital Tuning

Range ±2x10⁻⁸
 Resolution 1x10⁻¹²

Analog Tuning

Range ±2.2x10⁻⁸
 Resolution 1x10⁻¹¹

Input 0-2.5 V into 100 kΩ

Warm-up Time <180 s

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)

^{**} All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Part number 090-02984-006

Specification

All specifications at 25 °C, V_{CC} = 3.3 VDC unless otherwise specified.

Electrical Specification

RF Output

Frequency	5 MHz
Format	CMOS
 Amplitude 	0 V to Vcc
 Load impedance 	1 MΩ
 Quantity 	1

1 PPS Output

•	Rise/fall time (10%-90%) at	
	load capacitance 10 pF	<10 ns
•	Pulse width	100 µs
•	Level	0 V to Vcc
•	Logic High (VoH) min	2.80 V
•	Logic Low (VoL) max	0.30 V
•	Load impedance	1 MΩ
•	Quantity	1

1 PPS Input

•	Format	Rising edge
•	Low level	<0.5 V
•	High level	2.5 V to Vcc
•	Input impedance	1 MΩ
•	Quantity	1

Serial Communications

 Protocol 	RS-232
Format	CMOS 0 V to Vcc
 Tx/Rx impedance 	1 ΜΩ
Baud rate	57600

Built-in Test Equipment (BITE) output

•	Format	CMOS 0 V to Vcc
•	Load impedance	1 ΜΩ
•	Logic	0 = Normal operation
		1 = Alarm

Power Input

•	Operating	<120 mW
•	Warmup	<140 mW
•	Input Voltage (Vcc)	$3.3 \pm 0.1 \text{ VDC}$

Physical Specifications

•	Size	1.6" x 1.39" x 0.45"
•	Weight	<35 g

	ATDE	100,000,1
•	MTBF	>100,000 hours

Environmental Specification

Operating

•	Operating	temperature	–10 °C to 70 °C
•	Maximum	frequency change	
		and the same of th	

over operating temp range (max. rate of change

0.5 °C/minute) $\pm 5 \times 10^{-10}$

 Frequency change over allowable input voltage range $\pm 4x10^{-10}$

Magnetic sensitivity (≤2.0 Gauss) ±9x10⁻¹¹/Gauss

 Radiated emissions Compliant to FCC part 15, Class B, when mounted properly onto host PCB.

 Vibration Maintains lock under

MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

 Humidity 0 to 95% RH per MIL-STD-810, Method 507.4.

Storage and Transport (non-operating)

•	Temperature	–55 °C to 85 °C
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• Shock (1 ms half-sine) 1000 g

 Vibration MIL-STD-810, Method 514.5,

Procedure 1, 7.7 grms

Performance Parameters

Stability (Allan Deviation) ADEV

•	TAU = 1 sec	3.0x10 ⁻¹⁰
•	TAU = 10 sec	1.0x10 ⁻¹⁰
•	TAU = 100 sec	$3.0x10^{-11}$
•	TAU = 1000 sec	1 0x10 ⁻¹¹

RF Output Phase Noise (SSB)

•	1 Hz	<-53 dBc/Hz
•	10 Hz	<-73 dBc/Hz
•	100 Hz	<-116 dBc/Hz
•	1000 Hz	<-131 dBc/Hz
•	10000 Hz	<-138 dBc/Hz
•	100,000 Hz	<-140 dBc/Hz

Frequency Accuracy

 Maximum offset at shipment 	$\pm 5 \times 10^{-11}$
 Maximum retrace (48 hrs off) 	$\pm 5 \times 10^{-10}$
 Aging, monthly* 	<9x10 ⁻¹⁰ typical**
 Aging, yearly* 	<1x10 ⁻⁸ typical**
• 1 PPS Sync.	±100 ns

(*After 30 days of continuous operation)

^{**} All CSAC units are tested for aging specs as per the datasheet and meet the specs at the time of shipment. However, continuous operation of CSAC over extended period of time may yield unpredictable aging performance, resulting in failure to meet the aging specs and may not be suitable for certain applications.



Quantum™ SA.45s CSAC Option 006 cont.

Part number 090-02984-006

Digital Tuning

 $\pm 2x10^{-8}$ Range Resolution 1x10⁻¹²

Analog Tuning

 Range ±2.2x10⁻⁸ 1x10⁻¹¹ Resolution

0-2.5 V into $100 \text{ k}\Omega$ Input

Warm-up Time <180 s

Solder

Hand solder using 63/37 Tin/Lead Solder with maximum soldering tip of 329 °C (625 °F)



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